

Product Change Notification / LIAL-09VUUA424

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27-Dec-2022

Product Category:

Ethernet Controllers, Ethernet PHYs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5151 Final Notice: Qualification of a new lead frame DAP surface prep material for selected KSZ8041xx, SPNZ80105xx and KSZ8851xx device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

Affected CPNs:

LIAL-09VUUA424_Affected_CPN_12272022.pdf LIAL-09VUUA424_Affected_CPN_12272022.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of a new lead frame DAP surface prep material for selected KSZ8041xx, SPNZ80105xx and KSZ8851xx device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change					
Assembly Site	Microchip Technology Thailand	Microchip Technology Thailand					
	(HQ) (MTAI)	(HQ) (MTAI)					
Wire Material	Au/2N	Au/2N					
Die Attach Material	3280	3280					
Molding Compound Material	G700LTD	G700LTD					
Lead-Frame Material	A194	A194					
Lead Frame DAP Surface	Ag selective plating	Ag selective plating (Add more Ag area)					
Prep	See Pre and Post Change Si	ummary for comparison.					

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity by qualifying a new lead frame DAP surface prep material.

Change Implementation Status:In Progress

Estimated First Ship Date: January 20, 2023 (date code: 2303)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2022				^	December 2022					January 2023					
Morkwook	2	2	2	2		4	5	5	5	5	1	2	3	4	5	
Workweek	3	4	5	6		9	0	1	2	3						
Initial PCN Issue			, , ,													
Date			Х													
Qual Report										.,						
Availability										Х						
Final PCN Issue										.,						
Date										Х						
Estimated													>			
Implementation													X			

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Date										

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 15, 2022: Issued initial notification.

December 27, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on January 20, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-09VUUA424_ Qualification Report.pdf PCN_LIAL-09VUUA424_Pre and Post Change Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

KSZ8041NL

KSZ8041RNL

SPNZ801059

KSZ8041NLI

KSZ8041RNLI

KSZ8041NL-TR

KSZ8041RNL-TR

SPNZ801059-TR

KSZ8041NLI-TR

KSZ8041RNLI-TR

KSZ8851SNL

KSZ8851SNLI

KSZ8851SNL-TR

KSZ8851SNLI-TR